

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices – Mechanical and climatic test methods –
Part 20: Resistance of plastic encapsulated SMDs to the combined effect of
moisture and soldering heat**

**Dispositifs à semiconducteurs – Méthodes d’essais mécaniques
et climatiques –
Partie 20: Résistance des CMS à boîtier plastique à l’effet combiné
de l’humidité et de la chaleur de brasage**



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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.080.01

ISBN 978-2-8322-8727-9

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CONTENTS

FOREWORD	4
1 Scope	6
2 Normative references	6
3 Terms and definitions	6
4 General description	7
5 Test apparatus and materials	7
5.1 Humidity chamber	7
5.2 Reflow soldering apparatus	8
5.3 Holder	8
5.4 Wave-soldering apparatus	8
5.5 Solvent for vapour-phase reflow soldering	8
5.6 Flux	8
5.7 Solder	8
6 Procedure	9
6.1 Initial measurements	9
6.1.1 Visual inspection	9
6.1.2 Electrical measurement	9
6.1.3 Internal inspection by acoustic tomography	9
6.2 Drying	9
6.3 Moisture soak	9
6.3.1 General	9
6.3.2 Conditions for non-dry-packed SMDs	9
6.3.3 Moisture soak for dry-packed SMDs	10
6.4 Soldering heat	11
6.4.1 General	11
6.4.2 Method of heating by infrared convection or convection reflow soldering	12
6.4.3 Method of heating by vapour-phase reflow soldering	13
6.4.4 Method of heating by wave-soldering	13
6.5 Recovery	14
6.6 Final measurements	15
6.6.1 Visual inspection	15
6.6.2 Electrical measurement	15
6.6.3 Internal inspection by acoustic tomography	15
7 Information to be given in the relevant specification	15
Annex A (informative) Details and description of test method on resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	17
A.1 Description of moisture soak	17
A.1.1 Guidance for moisture soak	17
A.1.2 Considerations on which the condition of moisture soak is based	17
A.2 Procedure for moisture content measurement	22
A.3 Soldering heat methods	23
A.3.1 Temperature profile of infrared convection and convection reflow soldering	23
A.3.2 Temperature profile of vapour-phase soldering	25
A.3.3 Heating method by wave-soldering	26

Figure 1 – Method of measuring the temperature profile of a specimen.....	8
Figure 2 – Heating by wave-soldering	14
Figure A.1 – Process of moisture diffusion at 85 °C, 85 % RH.....	18
Figure A.2 – Definition of resin thickness and the first interface	18
Figure A.3 – Moisture soak time to saturation at 85 °C as a function of resin thickness.....	18
Figure A.4 – Temperature dependence of saturated moisture content of resin	19
Figure A.5 – Dependence of moisture content of resin at the first interface on resin thickness under various soak conditions	20
Figure A.6 – Dependence of moisture content of resin at the first interface on resin thickness related to method A of moisture soak	20
Figure A.7 – Dependence of the moisture content of resin at the first interface on resin thickness related to method B of moisture soak	21
Figure A.8 – Dependence of moisture content of resin at the first interface on resin thickness related to condition B2 of method B of moisture soak	22
Figure A.9 – Temperature profile of infrared convection and convection reflow soldering for Sn-Pb eutectic assembly	23
Figure A.10 – Temperature profile of infrared convection and convection reflow soldering for lead-free assembly	24
Figure A.11 – Classification profile.....	25
Figure A.12 – Temperature profile of vapour-phase soldering (condition II-A)	25
Figure A.13 – Immersion method into solder bath	26
Figure A.14 – Relation between the infrared convection reflow soldering and wave-soldering.....	27
Figure A.15 – Temperature in the body of the SMD during wave-soldering.....	27
Table 1 – Moisture soak conditions for non-dry-packed SMDs	9
Table 2 – Moisture soak conditions for dry-packed SMDs (method A)	10
Table 3 – Moisture soak conditions for dry-packed SMDs (method B)	11
Table 4 – SnPb eutectic process – Classification reflow temperatures (T_C)	12
Table 5 – Pb-free process – Classification reflow temperatures (T_C)	13
Table 6 – Heating condition for vapour-phase soldering	13
Table 7 – Immersion conditions for wave-soldering	14
Table A.1 – Comparison of actual storage conditions and equivalent moisture soak conditions before soldering heat	19
Table A.2 – Classification profiles	24

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 20: Resistance of plastic encapsulated SMDs to
the combined effect of moisture and soldering heat**

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International Standard IEC 60749-20 has been prepared by IEC technical committee 47: Semiconductor devices.

This third edition cancels and replaces the second edition published in 2008. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) incorporation of a technical corrigendum to IEC 60749-20:2008 (second edition);
- b) inclusion of new Clause 3;
- c) inclusion of explanatory notes.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2634/FDIS	47/2646/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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